ShinDengen

S1NB60-7062

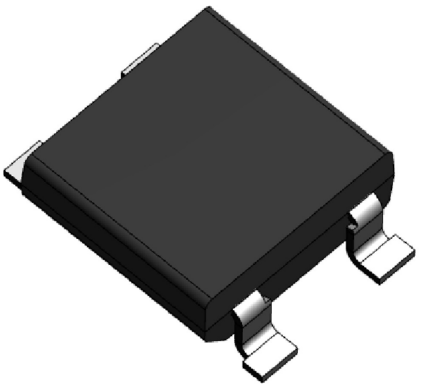
Bridge Diodes
600V, 1A

Feature

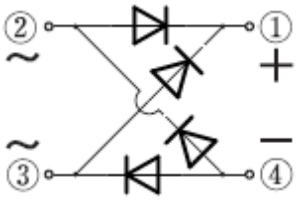
- Small SMD (There is also DIP)
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): 1N



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-40 to 150	°C
Junction temperature	Tj		-40 to 150	°C
Repetitive peak reverse voltage	V_{RRM}		600	V
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※	1	A
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Tl=122°C ※	1	A
Surge forward current	I_{FSM}	50Hz sine wave, Non-repetitive 1 cycle peak value, Tj=25°C	30	A
Current squared time	I^2t	1ms≦tp＜10ms, Tj=25°C, per diode	4.5	A^2s

※ ：See the original Specifications

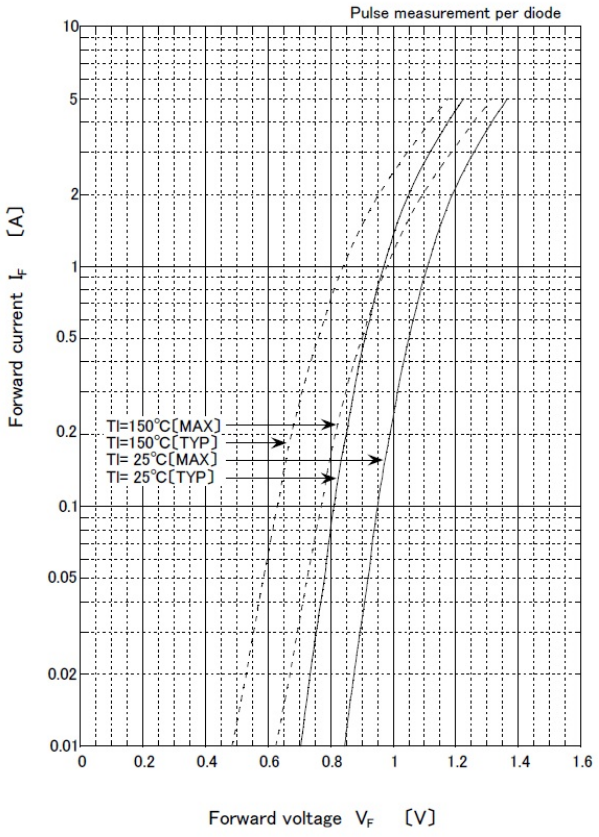
Electrical Characteristics (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	V_F	IF=0.5A, Pulse measurement, per diode			1.05	V
Reverse current	I_R	VR=600V, Pulse measurement, per diode			10	μA
Thermal resistance	Rth(j-l)	Junction to lead ※			15	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate ※			68	°C/W

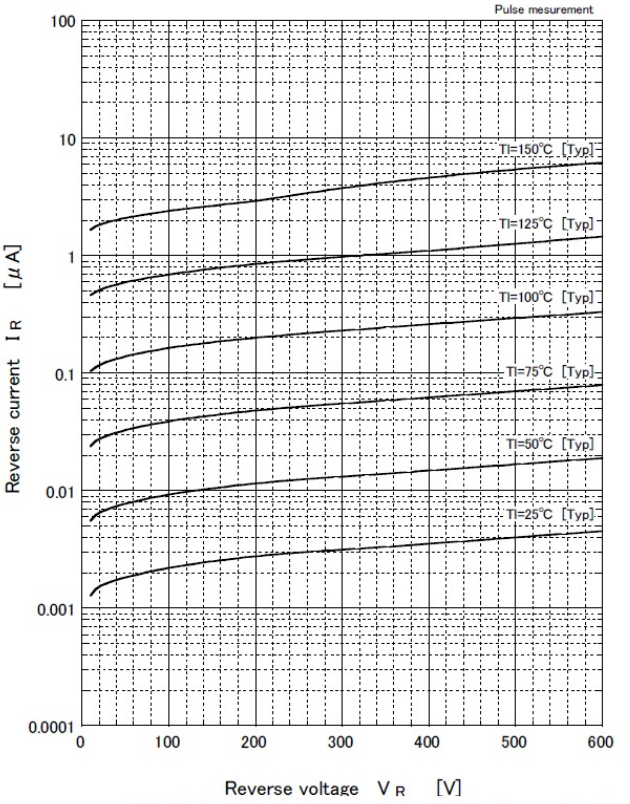
※ ：See the original Specifications

CHARACTERISTIC DIAGRAMS

Forward voltage

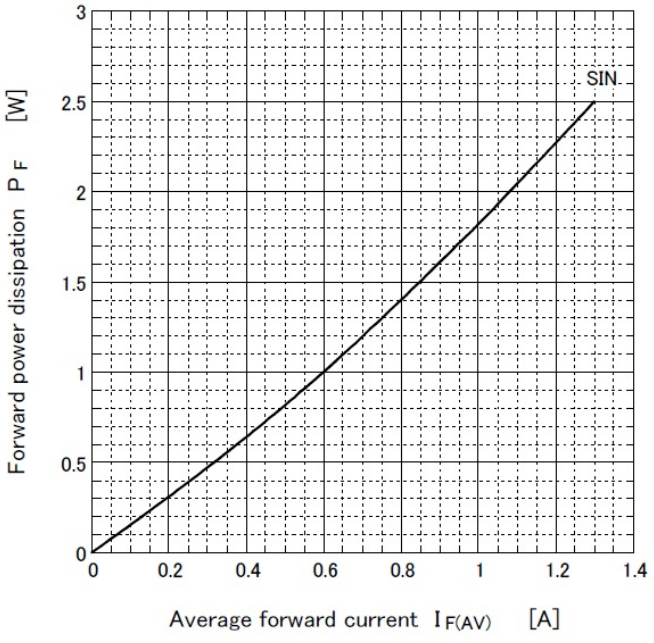


Reverse current



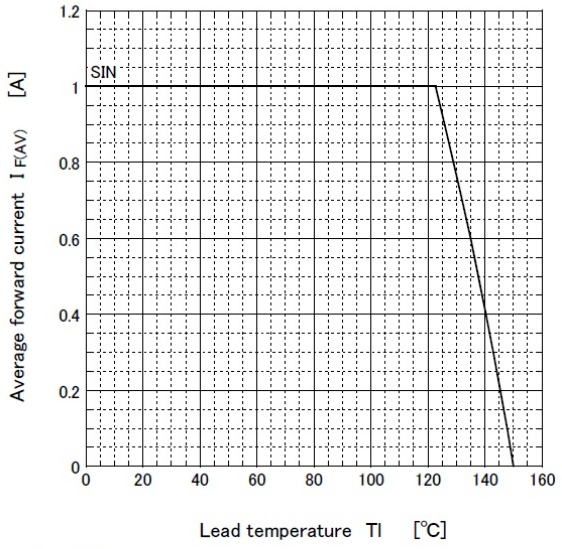
Note: The above characteristics curves are presented for reference only and not guaranteed by production test,unless otherwise noted.

Forward power dissipation



●Tj =150℃

Derating curve

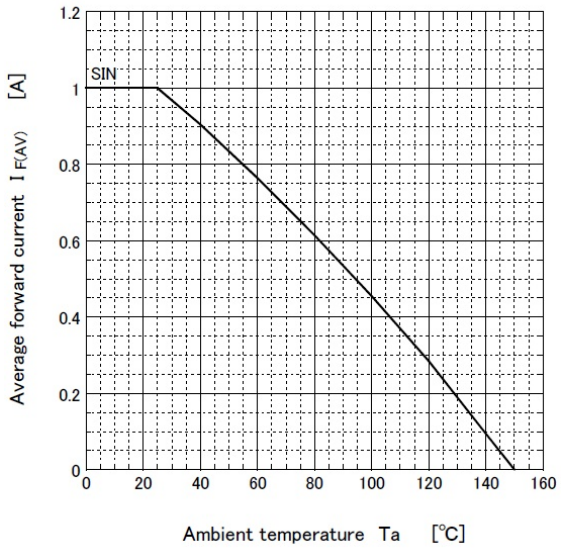


●V_R = 600V
Sine wave
R-load
Free in air

●Substrate detail

Type	Glass-epoxy
Size	150mm×90mm
Thickness	1mm
Conductor thickness	35μm
Pattern area	360mm²

Derating curve

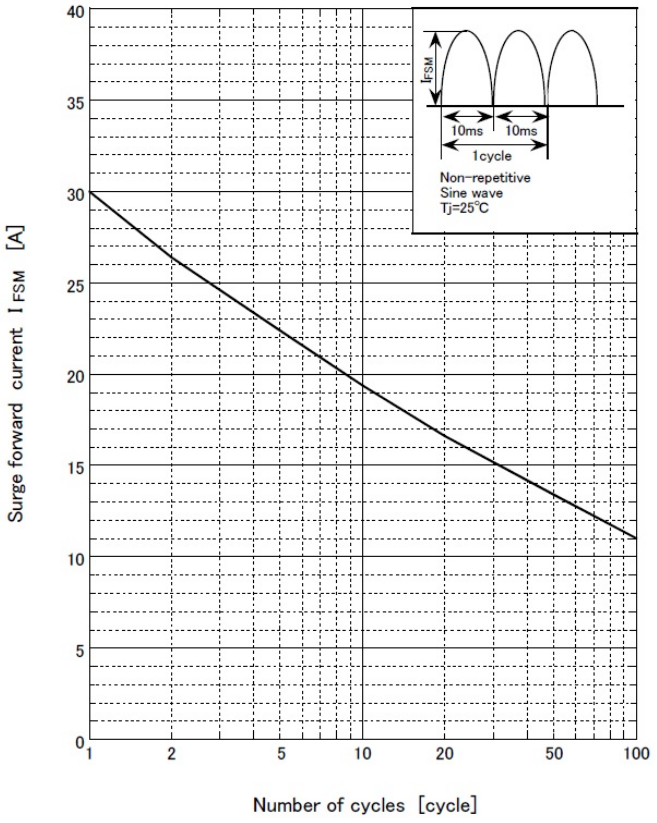


●V_R = 600V
Sine wave
R-load
Free in air

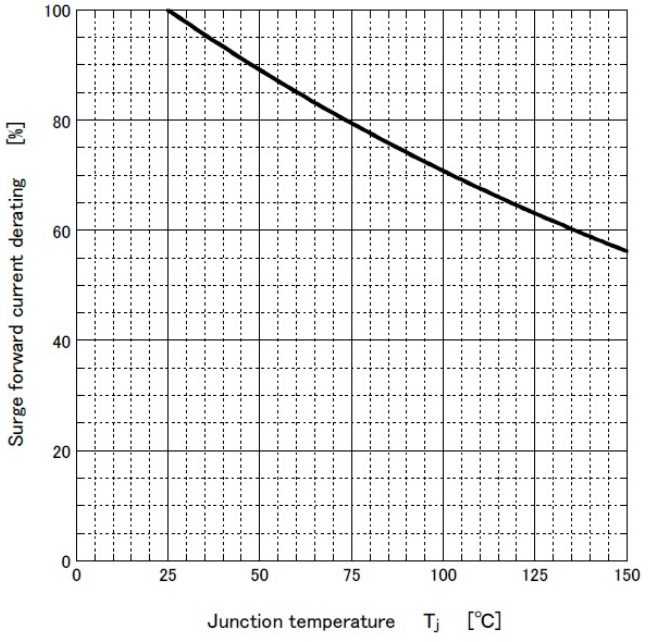
●Substrate detail

Type	Glass-epoxy
Size	150mm×90mm
Thickness	1mm
Conductor thickness	35μm
Pattern area	360mm²

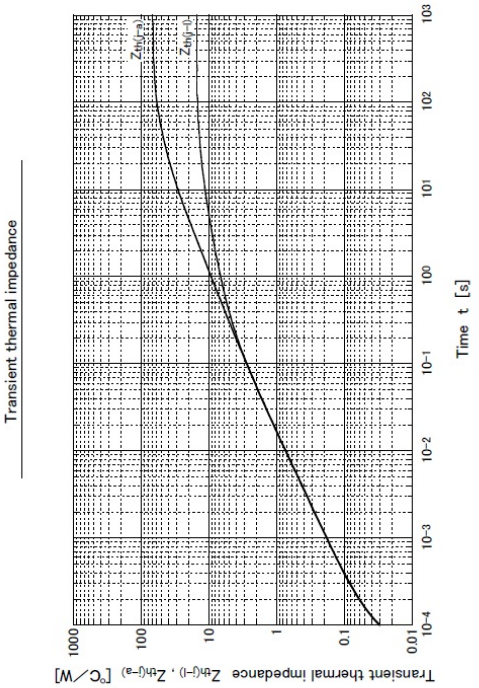
Surge forward current capability



Surge forward current derating vs Junction temperature



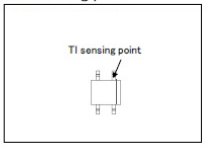
Transient thermal impedance



●Substrate detail

Type	Glass-epoxy
Size	150mm×90mm
Thickness	1mm
Conductor thickness	35μm
Pattern area	360mm²

●TI sensing point

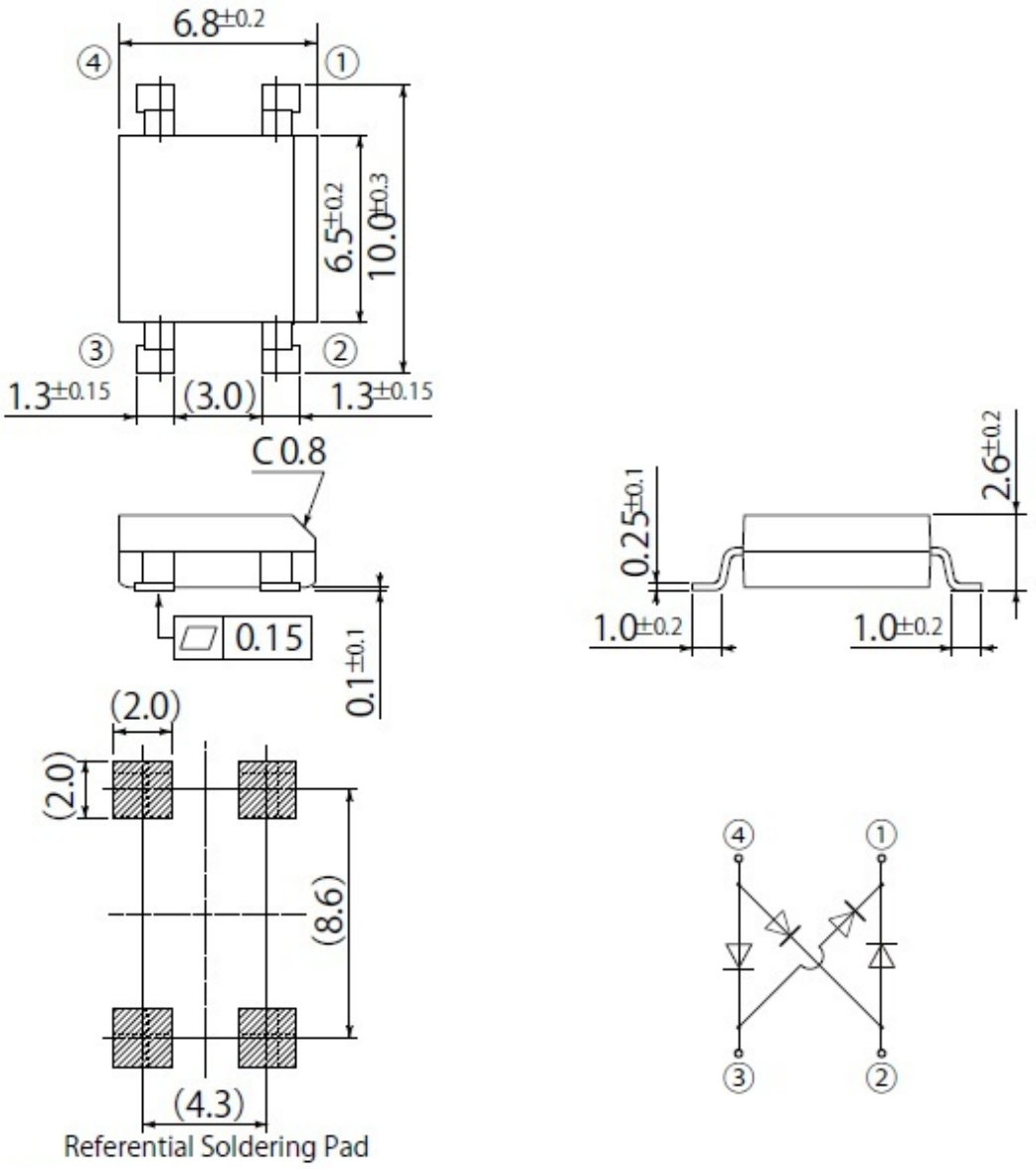


Outline Dimensions

unit:mm

C4

JEDEC Code	–
JEITA Code	–
House Name	1N(SMD)



・Optimize soldering pad to the board design and soldering condi tion.

・The content specified herein is subject to change for improvement without notice.
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U182-1(2026.09)

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